

SPECIFICATIONS

Terminals:

Brass; Copper Alloy (C36000), ASTM-B-16

Contacts:

Beryllium Copper; Copper Alloy (C17200),
ASTM-B-194

Plating:

- Gold over Nickel

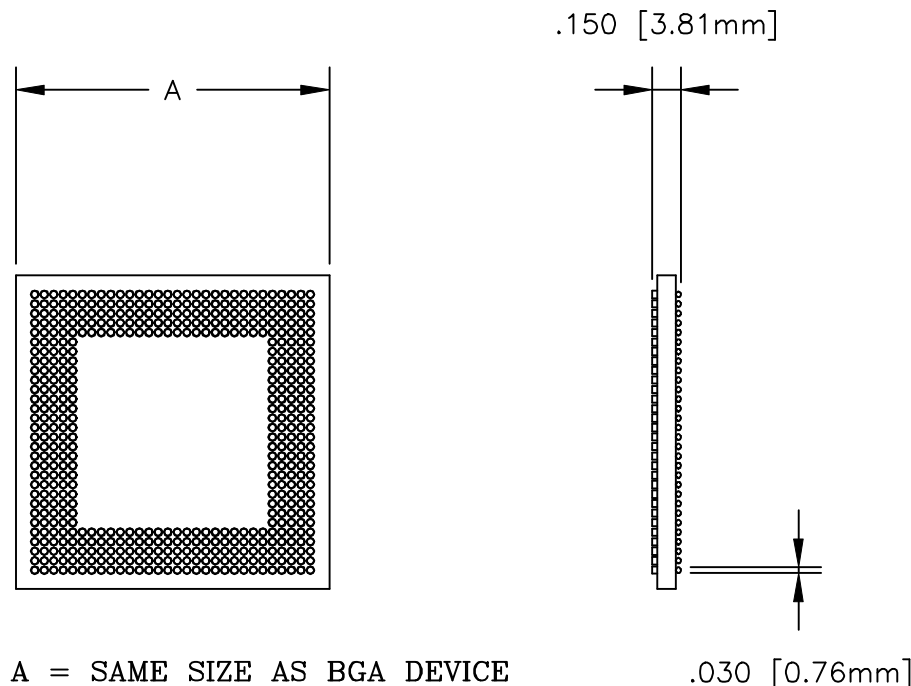
Body Material:

- Molded PPS (High Temp. Glass Filled Thermoplastic), U.L. Rated 94V-0, -60°C to 260°C (-76°F to 500°F)

- FR-4 Glass Epoxy, U.L. Rated 94V-0

Solder Ball:

63Sn/37Pb, Eutectic, 183°C (361.4°F)



A = SAME SIZE AS BGA DEVICE

DESCRIPTION

BPE-XXX-2-XXX-BL


BALL COUNT _____

PITCH=1.27mm _____

GRID SIZE(eg.020) _____

BALLS ON BOTTOM _____

ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE SPECIFIED

	Emulation Technology, Inc. — VLSI and SMT ADAPTERS and ACCESSORIES —	
	2344 Walsh Avenue, Bldg. F Santa Clara, Ca 95051	TEL:(408)982-0660 FAX:(408)982-0664
SHEET: 1 OF 1	DATE: 4-28-00	REVISION: _____
ASSEMBLY DRAWING		
CHECKED: Paula Olson	DRAWN: Steve Martin	ITEM: BPE-XXX-2-XXX-B
DO NOT SCALE DRAWING		DESCRIPTION: BPE-XXX-2BGXXX-BL